



**THE DATASHEET OF
1N4148WSF-7**



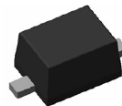
Features

- Fast Switching Speed
- Low Forward Voltage: Maximum of 0.715V at 1mA
- Fast Reverse Recovery: Maximum of 4ns
- Low Capacitance: Maximum of 1.5pF
- Low Leakage Current: Maximum of 500nA at 80V
- Small Surface Mount Package
- Thermally Efficient Copper Alloy leadframe for High Power Dissipation
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: SOD323F
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper Alloy leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Weight: 0.003 grams (approximate)

SOD323F



Top View

Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
1N4148WSF-7	Standard	JP	7	8	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



JP = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: A = 2013)
 M = Month (ex: 9 = September)

Date Code Key

Year	2013	2014	2015	2016	2017	2018	2019	2020
Code	A	B	C	D	E	F	G	H

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	71	V
Forward Continuous Current (Note 5)	I _{FM}	250	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	@ t = 1.0μs	4.0
		@ t = 1.0ms	1.0
		@ t = 1.0s	0.5

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	400	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	313	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	100	—	V	I _R = 100μA
Forward Voltage	V _F	—	0.715 0.855 1.0 1.25	V	I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA
Leakage Current (Note 6)	I _R	—	0.5 50 30 30	μA μA μA nA	V _R = 80V V _R = 80V, T _J = +150°C V _R = 25V, T _J = +150°C V _R = 25V
Total Capacitance	C _T	—	1.5	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

- Notes: 5. Device mounted on FR-4 PCB, on minimum recommended, 2oz copper pad layout.
6. Short duration pulse test used to minimize self-heating effect.

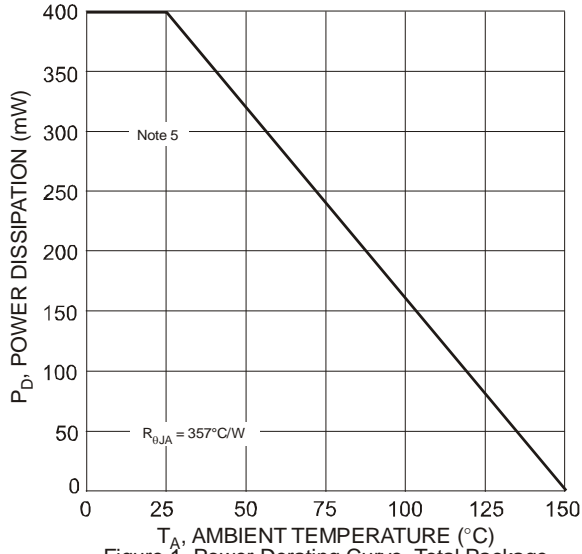


Figure 1 Power Derating Curve, Total Package

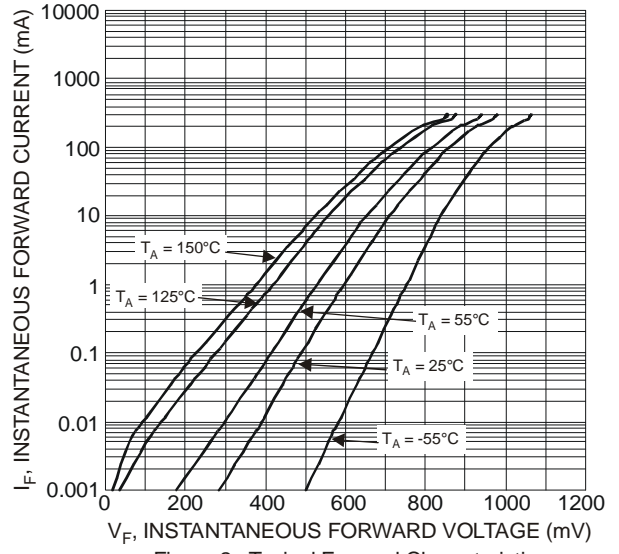


Figure 2 Typical Forward Characteristics

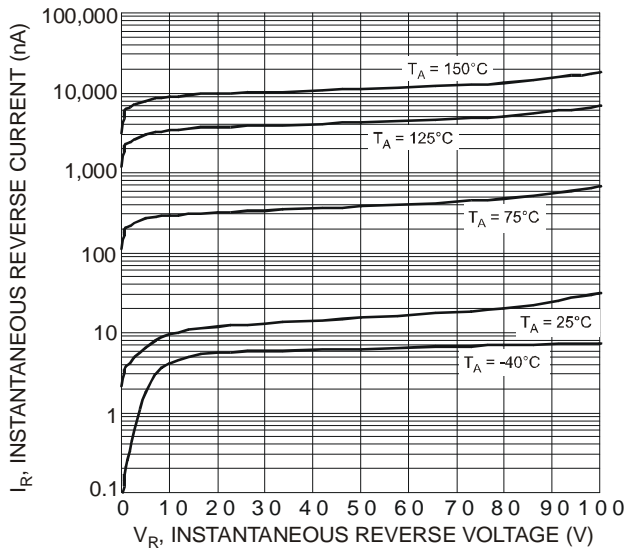


Figure 3 Typical Reverse Characteristics

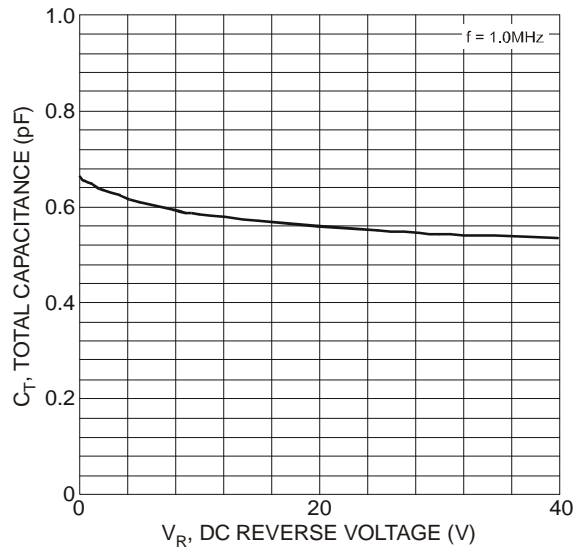
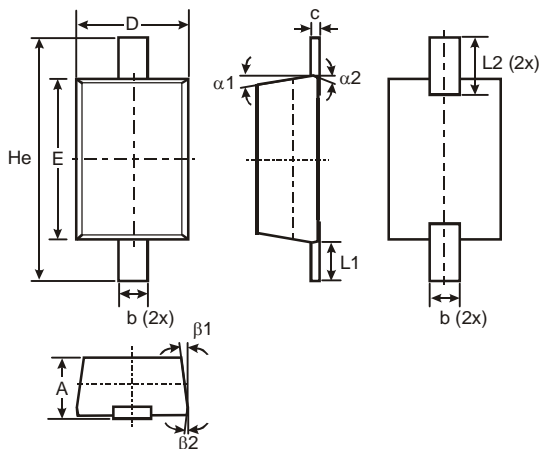


Figure 4 Total Capacitance vs. Reverse Voltage

Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

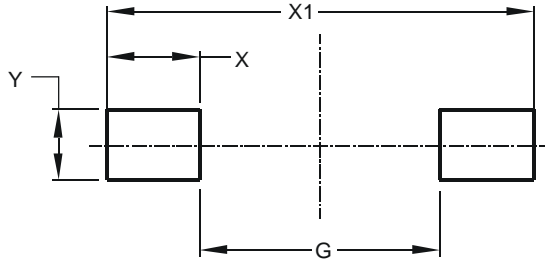


SOD323F			
Dim	Min	Max	Typ
A	0.60	0.75	-
b	0.25	0.35	-
c	0.05	0.26	-
D	1.15	1.35	1.25
E	1.60	1.80	1.70
He	2.30	2.70	2.50
L1	0.30	0.50	0.40
L2	0.41	0.61	0.51
α1	-	-	7°
α2	-	-	3°
β1	-	-	7°
β2	-	-	3°

All Dimensions in mm

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
G	1.280
X	0.710
X1	2.700
Y	0.403

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